



[ABSTRACT]

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The present invention relates to a lead frame and a heat sink-attached semiconductor package using the lead frame. More particularly, the present invention relates to a lead frame and a heat sink-attached semiconductor package fabric using the lead frame to obtain a smooth flow of melted encapsulating resin in a molding process, to achieve an easy fabrication, in addition, to exhibit superior heat discharge characteristics. The semiconductor package comprises a heat sink of a substantially rectangular or square shape having a predetermined thickness; a semiconductor chip bonded to the top surface of the heat sink by means of a nonconductive adhesive tape; a plurality of inner leads attached to the outer peripheral portion of the upper surface of the heat sink by means of adhesive tapes, each inner leads having a width which increases as it extends towards the semiconductor chip and a space defined between those adjacent ones of those inner leads being gradually reduced as they extend toward the semiconductor chip; a plurality of outer leads extended to the inner leads; and an encapsulating portion formed by applying an encapsulating material to the heat sink, the semiconductor chip, the inner leads and the conductive wires.

[Main Drawing]

Fig. 7